

STPS2H100RL

High voltage power Schottky rectifier

Features

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Avalanche capability specified

Description

Axial power Schottky rectifier suited for switch mode power supply and high frequency DC/DC converters. Packaged in DO-41, this device is intended for use in low voltage, high frequency inverters and small battery chargers.

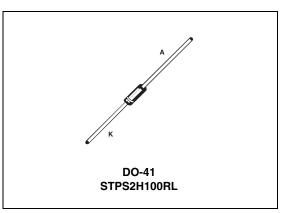


Table 1.Device summary

Symbol	Value
I _{F(AV)}	2 A
V _{RRM}	100 V
T _j (max)	175 °C
V _F (max)	0.70 V

1 Characteristics

Symbol	Paramet	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage		100	V
I _{F(RMS)}	Forward rms current		10	А
I _{F(AV)}	Average forward current	$T_{L} = 120 \ ^{\circ}C, \ \delta = 0.5$	2	Α
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	50	А
I _{RRM}	Repetitive peak reverse current	t _p = 2 ms square, F = 1 kHz	50	А
P _{ARM}	Repetitive peak avalanche power $t_p = 1 \ \mu s, T_j = 25 \ ^{\circ}C$		1500	W
T _{stg}	Storage temperature range	· · · ·	-65 to + 175	°C
Тj	Operating junction temperature ⁽¹⁾			°C
dV/dt	Critical rate of rise of reverse voltage			V/µs

1. $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3.Thermal resistance

Symbol	Parameter		Value	Unit
R _{th(j-a)}	Junction to ambient	Lead length = 10 mm	100	°C/W
R _{th(j-l)}	Junction to lead		35	C/ VV

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}			1	μA
		T _j = 125 °C			0.2	0.5	mA
V _F ⁽²⁾	Forward voltage drop	T _j = 25 °C	I _F = 2 A			0.86	
		T _j = 125 °C			0.65	0.70	V
		T _j = 25 °C	I _F = 4 A			0.92	
		T _j = 125 °C			0.72	0.78	

1. Pulse test: $t_p = 5 \text{ ms}, \delta < 2\%$

2. Pulse test: $t_p = 380 \ \mu s, \ \delta < 2\%$

To evaluate the conduction losses use the following equation: P = 0.62 x $I_{F(AV)}$ + 0.04 ${I_F}^2_{(RMS)}$



Average forward current versus

ambient temperature

Figure 1. Average forward current versus ambient temperature (δ = 0.5)

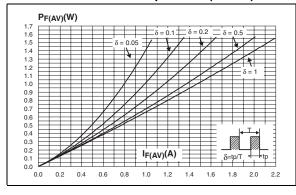


Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature

75

Tamb(°C)

100

125

150

175

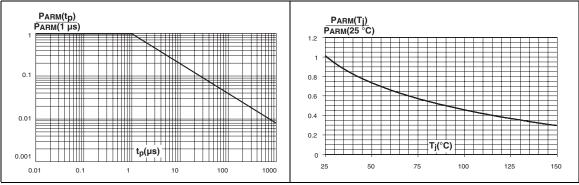


Figure 2.

2.2

2.0

1.8 1.6 1.4 1.2

1.0 0.8 0.6 0.4 0.2

0.0

0

IF(AV)(A)

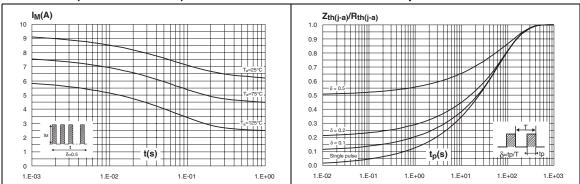
δ=tp/T

25

50

Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

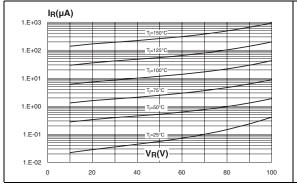
Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration

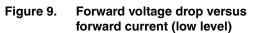


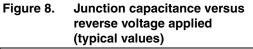
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Figure 7. Reverse leakage current versus reverse voltage applied (typical values)







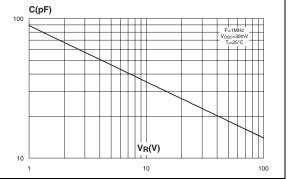


Figure 10. Forward voltage drop versus forward current (high level)

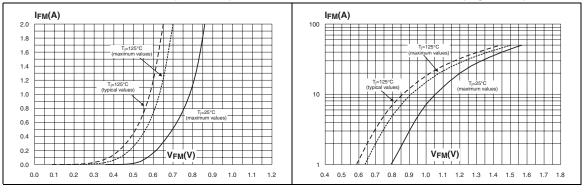
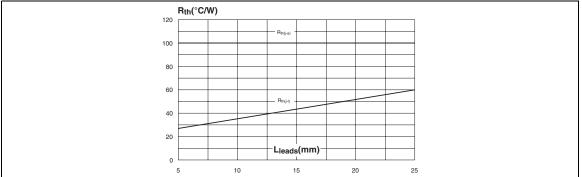


Figure 11. Thermal resistance versus lead length



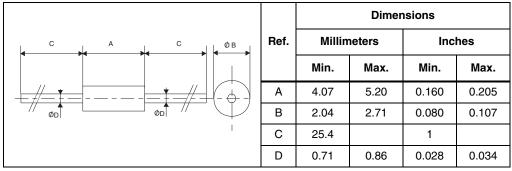


2 Package information

- Epoxy meets UL94, V0
- Band indicates cathode

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Table 5. DO-41 (plastic) dimensions





3 Ordering information

Table 6.Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS2H100	STPS2H100 Cathode ring	DO-41	0.34 q	2000	Ammopack
STPS2H100RL	STPS2H100 Cathode ring	00-41	0.54 y	5000	Tape and reel

4 Revision history

Table 7.Document revision history

Date	Revision	Changes	
Jul-2003	2A	Last update.	
23-Jun-2009	3	Updated dimension C in table 5.	
05-Oct-2009	4	Updated table 5 package dimensions.	



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